

# ***AOS Semiconductor Product Reliability Report***

**AOZ18103DI-02** rev A

**Plastic Encapsulated Device**

**ALPHA & OMEGA Semiconductor, Inc**

**[www.aosmd.com](http://www.aosmd.com)**

The AOS product reliability report summarizes the qualification results for AOZ18103DI-02 in DFN3X3-10L package. Accelerated environmental tests are performed on a specific sample size, samples are electrically tested before and after each stress time point. Review of final electrical test results confirm that AOZ18103DI-02 pass the AOS quality and reliability requirements. The released products will be categorized by its process family and routinely monitored for continuous improvement of product quality.

## I. AOZ18103DI-02 Reliability Stress Test Summary and Results

Test Item	Test Condition	Time Point	Sample Size / Lots	Number of Failures	Reference Standard
HTOL	$T_J = 125^{\circ}\text{C}$ , $V_{IN} = 20\text{V}$	168 / 500 / 1000 hours	231 pcs (3 lots)	0	JESD22-A108
Preconditioning (Note A)	$T_A = 85^{\circ}\text{C}$ , RH = 85% + 3 cycle reflow @ $260^{\circ}\text{C}$ (MSL 1)	168hours	924 pcs (3 lots)	0	JESD22-A113
HAST	$T_A = 130^{\circ}\text{C}$ , RH = 85%, P = 33.3psia, $V_{IN} = 20\text{V}$	96 hours	231 pcs (3 lots)	0	JESD22-A110
Temperature Cycle	$T_A = -65^{\circ}\text{C}$ to $150^{\circ}\text{C}$ , air to air	500 / 1000 cycles	231 pcs (3 lots)	0	JESD22-A104
HTSL	$T_A = 150^{\circ}\text{C}$	1000 hours	231 pcs (3 lots)	0	JESD22-A103
Autoclave	$T_A = 121^{\circ}\text{C}$ , RH = 100%, P = 29.7psia	96 hours	231 pcs	0	JESD22-A102
HTGB (MOSFET)	$T_J = 150^{\circ}\text{C}$ , $V_{GS} = 5\text{V}$	168 / 500 hours	231 (3 lots)	0	JESD22-A108
HTRB (MOSFET)	$T_J = 150^{\circ}\text{C}$ , $V_{DS} = 18\text{V}$	168 / 500 hours	231 (3 lots)	0	JESD22-A108

**Note:** The reliability data presents total of available generic data up to the published date.

Note A: MSL (Moisture Sensitivity Level) 1 based on J-STD-020

## II. Reliability Evaluation

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the product technology. Failure Rate Determination is based on JEDEC Standard JESD 85.

**FIT rate (failures per billion device hours): 2.939**

**MTTF = 340.3 million hrs=38844.25 years**

**Condition:**  $V_o = 5.5\text{V}$ ,  $T_o = 55^{\circ}\text{C}$ ,  $V_{s(IC)} = 20\text{V}$ ,  $V_{s(MOSFET)} = 18\text{V}$ ,  $T_{s(IC)} = 125^{\circ}\text{C}$  and  $T_{s(MOSFET)} = 150^{\circ}\text{C}$

**Accumulated Sample Size x Hours:** MOSFET = 280000, IC = 1077320

The failure rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \chi^2[CL, (2f+2)] / 2 \times [1/(SS \times t \times AF)]; \text{ [equation 1]} \quad \text{where} \quad \begin{array}{l} CL = \% \text{ of confidence level} \\ f = \text{number of failure} \\ SS = \text{sample size} \\ t = \text{stress time} \end{array}$$

Looking up the  $\chi^2/2$  table for zero failure (burn-in) with 60% confidence, the value of  $\chi^2[CL, (2f+2)] / 2$  is 0.92.

The Acceleration Factor (AF) is calculated from the following formula (both temperature and voltage acceleration factors are used in the final acceleration factor calculation) :

$$AF = AF_T \times AF_V = \exp[(E_a/k) \times (1/T_o - 1/T_s)] \times \exp[\beta (V_s - V_o)] \quad \text{where} \quad E_a = \text{activation energy}$$

$k$  = Boltzmann constant  
 $T_o$  = operating  $T_J$   
 $T_s$  = stress  $T_J$   
 $V_s$  = stress voltage  
 $V_o$  = operating voltage  
 $\beta$  = voltage acceleration coefficient

Assuming typical operating environment,  $V_o = 5.5V$ ,  $T_o = 55^\circ C$ ,  $E_a = 0.7eV$ ,  $V_{s(IC)} = 20V$ ,  $V_{s(MOSFET)} = 18V$ ,  $T_{s(IC)} = 125^\circ C$  and  $T_{s(MOSFET)} = 150^\circ C$ ,  $\beta = 0.5$  (silicon defect)

$$AF(DriverIC) = \exp \left[ \left( \frac{0.7}{8.617E - 5} \right) \cdot \left( \frac{1}{273 + 55} - \frac{1}{273 + 125} \right) \right] \cdot \exp[0.5 \cdot (20V - 5.5V)]$$

$$AF(MOSFET) = \exp \left[ \left( \frac{0.7}{8.617E - 5} \right) \cdot \left( \frac{1}{273 + 55} - \frac{1}{273 + 150} \right) \right] \cdot \exp[0.5 \cdot (18V - 5.5V)]$$

Substituting the values in equation 1, we have

$$\lambda = 0.92 \cdot \frac{1}{\text{Sample Size} \cdot \text{Stress Duration} \cdot AF(MOSFET)} + \frac{1}{\text{sample Size} \cdot \text{Stress Duration} \cdot AF(DriverIC)} hr^{-1}$$

$\lambda = 2.939 \cdot 10^{-9} hr^{-1}$  or 2.939 FIT; MTTF =  $(1/\lambda) = 340.3$  million hrs = 38844.24 years

The calculation shows failure rate is 2.939 FIT, MTTF is 340.3 million hours under typical operating conditions.

### III. AOZ18103DI-02 ESD and Latch Up Test Results

Test	Test Conditions	Total Sample Size	Number of Failures	Reference Standard
Electrostatic Discharge Human Body Model	$T_A = 25^\circ C$ , +/-4kV	10	0	JESD-A114
Electrostatic Discharge Charged Device Model	$T_A = 25^\circ C$ , +/-1kV	10	0	JESD-C101
Latch Up	$T_A = 25^\circ C$ , +/-100mA, 1.27x OV	10	0	JESD78
Latch Up	$T_A = 125^\circ C$ , +/-100mA, 1.27x OV	10	0	JESD78

**Note:** ATE results are used to determine PASS/FAIL. Parametric shift<10%.

